

10/06/3870
05/21/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

7661089

APPL NUM 10063870	FILING DATE 05/21/2002	CLASS 228	SUBCLASS 102	GAU 1725	EXAMINER TRAN
**APPLICANTS: Araki Chihiro;					
**CONTINUING DATA VERIFIED: none					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2001-161742 05/30/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials				SIMTEK6353	
TITLE : Wire bonding method and apparatus therefor					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims <input type="checkbox"/> Print Claim for O.G. <input type="checkbox"/>
ISSUE FEE		Primary Examiner	DRAWING
Amount Due	Date Paid		Sheet Drwg. <input type="checkbox"/> Figs. Drwg. <input type="checkbox"/> Print Fig. <input type="checkbox"/>
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM
(Attached in pocket on right inside flap)